

## N-Ch 100V Fast Switching MOSFETs

## Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

## Product Summary

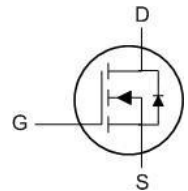
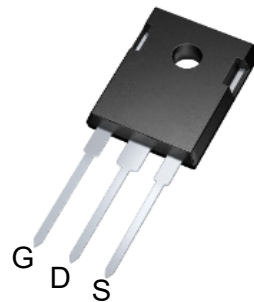


BVDSS	RDSON	ID
100V	2.0 mΩ	300A

## Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

## TO247 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	300	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	163	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	1028	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	583	mJ
$I_{AS}$	Avalanche Current	54	A
$P_D @ T_C = 25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	379	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	59	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	0.33	$^\circ\text{C/W}$

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
$\Delta BV_{DSS} / \Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	---	---	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=20A$	---	2.0	2.6	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	3	4	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	$mV/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=100V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=100V, V_{GS}=0V, T_J=100^\circ\text{C}$	---	---	100	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=20A$	---	76	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	2.3	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{DS}=50V, V_{GS}=10V, I_D=20A$	---	150	---	nC
$Q_{gs}$	Gate-Source Charge		---	32.5	---	
$Q_{gd}$	Gate-Drain Charge		---	49	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{GS}=10V, V_{DD}=50V,$ $R_G=3\Omega, I_D=20A$	---	27	---	ns
$T_r$	Rise Time		---	78.5	---	
$T_{d(off)}$	Turn-Off Delay Time		---	110	---	
$T_f$	Fall Time		---	86	---	
$C_{iss}$	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, f=1\text{MHz}$	---	9030	---	pF
$C_{oss}$	Output Capacitance		---	1505	---	
$C_{rss}$	Reverse Transfer Capacitance		---	40	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V$ , Force Current	---	---	300	A
$I_{SM}$	Pulsed Source Current <sup>2,4</sup>		---	---	1000	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=20A, di/dt=100A/\mu s$	---	90	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	175	---	nC

Note :

F The data is tested by a surface mounted on a 1/4 inch<sup>24</sup> FR-4 board with 20Z copper.G The data is tested by a pulsed pulse width  $\leq 300\mu s$  duty cycle  $\leq 2\%$ H The EAS data shows Max. Rating. The test condition is  $V_{RMG} \gg 0, V_{DD}=50V, V_{GS}=10V, L=0.4mH, I_{AS}=54A$ .I The power dissipation is limited by  $150^\circ\text{C}$  junction temperatureJ The data is theoretically the same as  $I_{D(on)}$  and  $I_{D(on)A}$ . In real applications, it should be limited by total power dissipation.

### Typical Characteristics

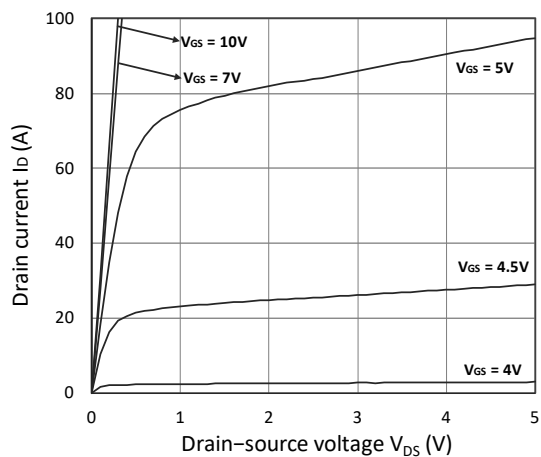


Figure 1. Output Characteristics

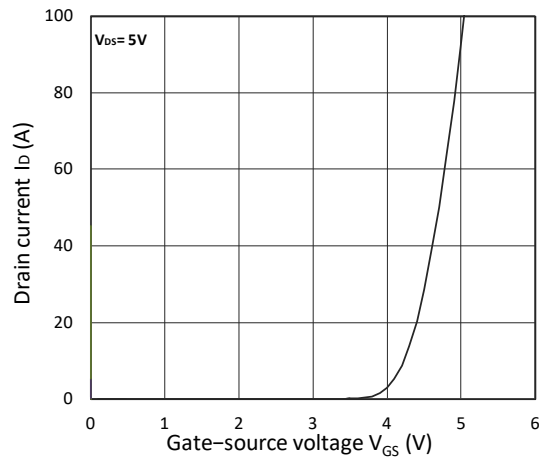


Figure 2. Transfer Characteristics

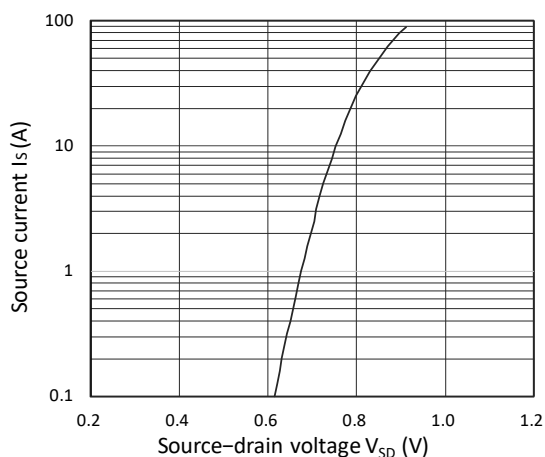


Figure 3. Forward Characteristics of Reverse

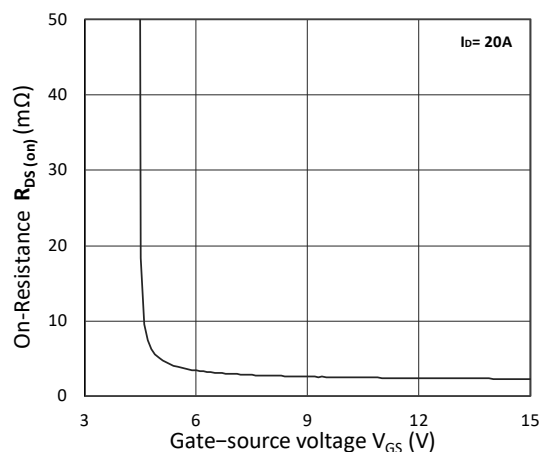


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$

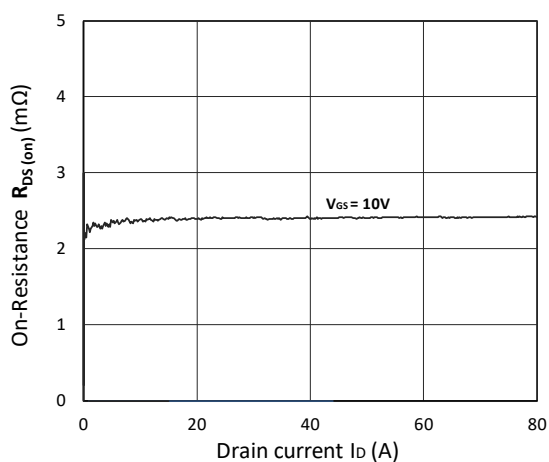


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$

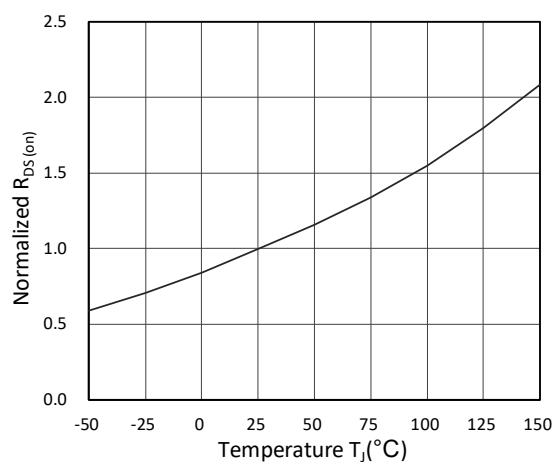


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

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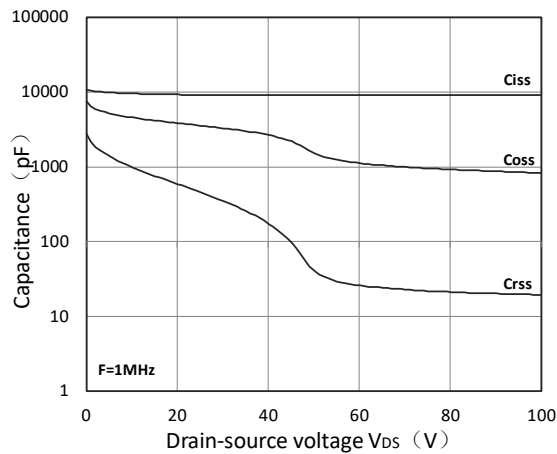


Figure 7. Capacitance Characteristics

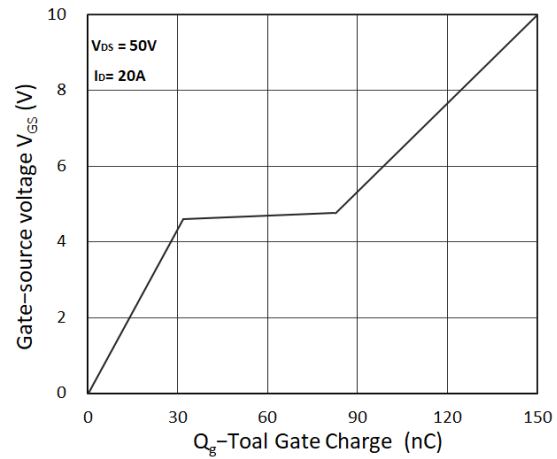


Figure 8. Gate Charge Characteristics

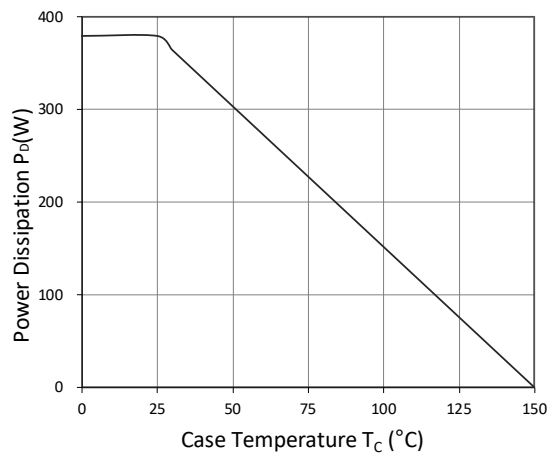


Figure 9. Power Dissipation

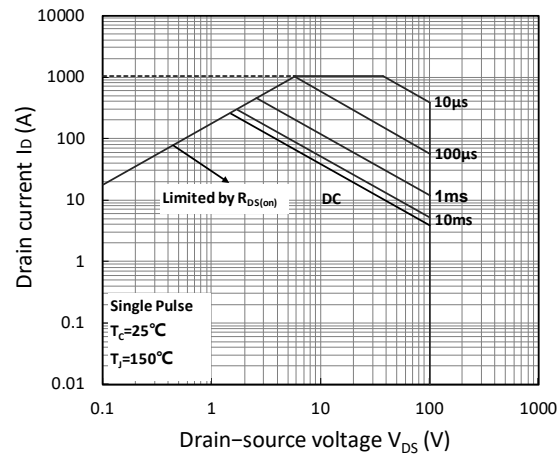


Figure 10. Safe Operating Area

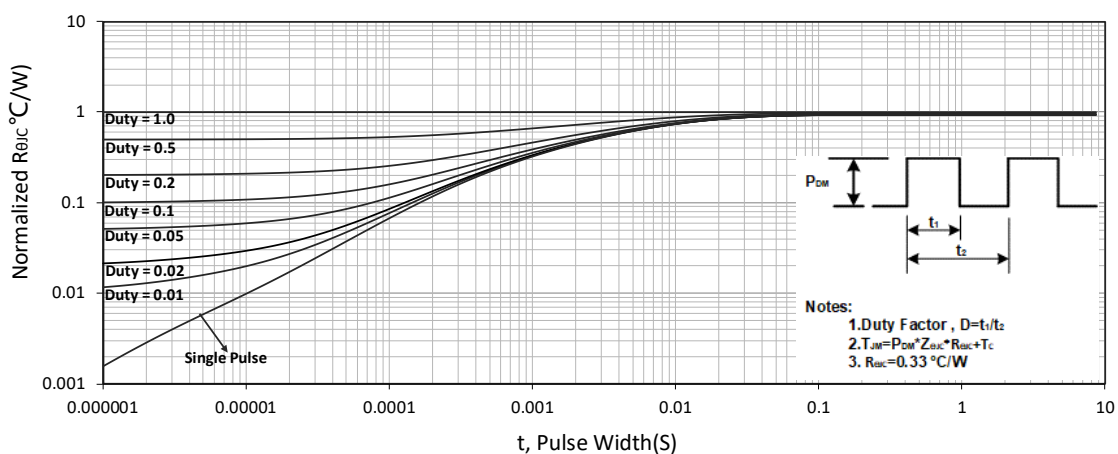


Figure 11. Normalized Maximum Transient Thermal Impedance

## Test Circuit

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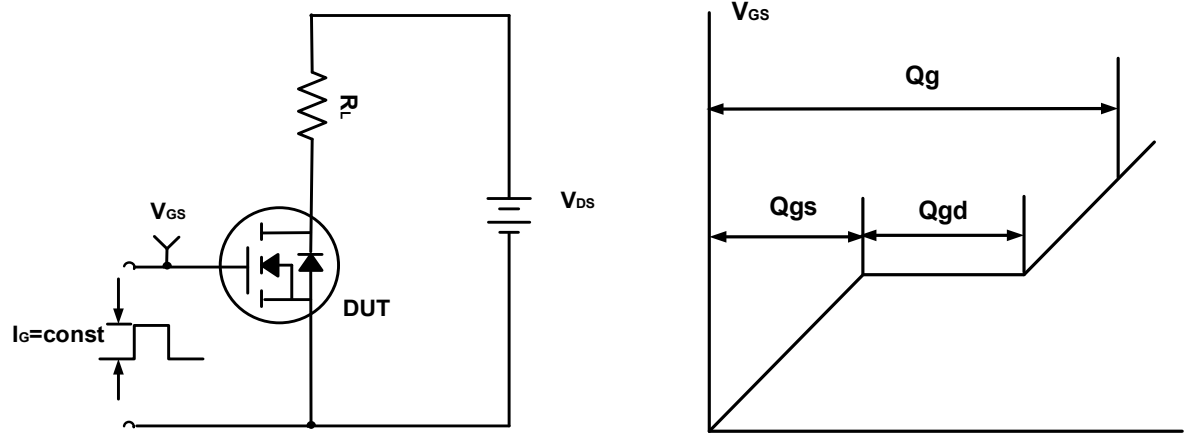


Figure A. Gate Charge Test Circuit & Waveforms

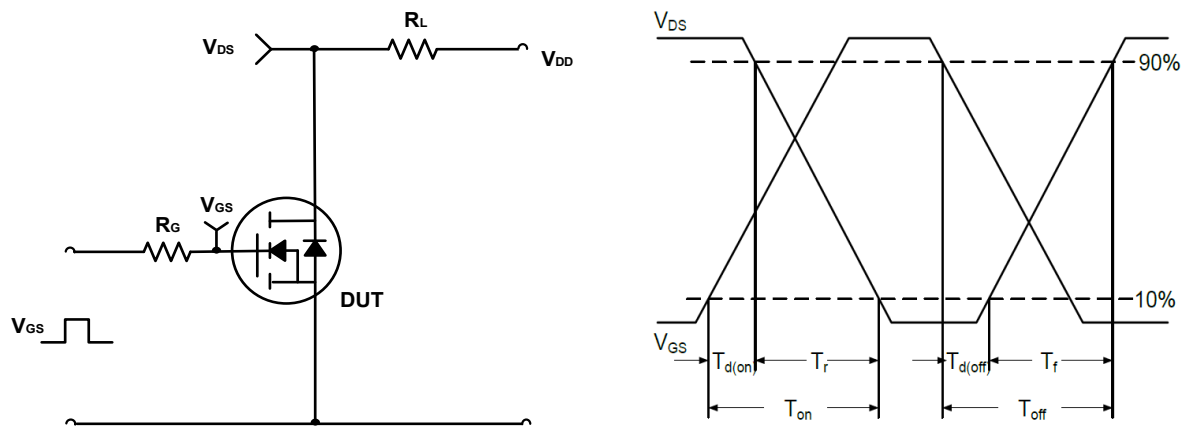
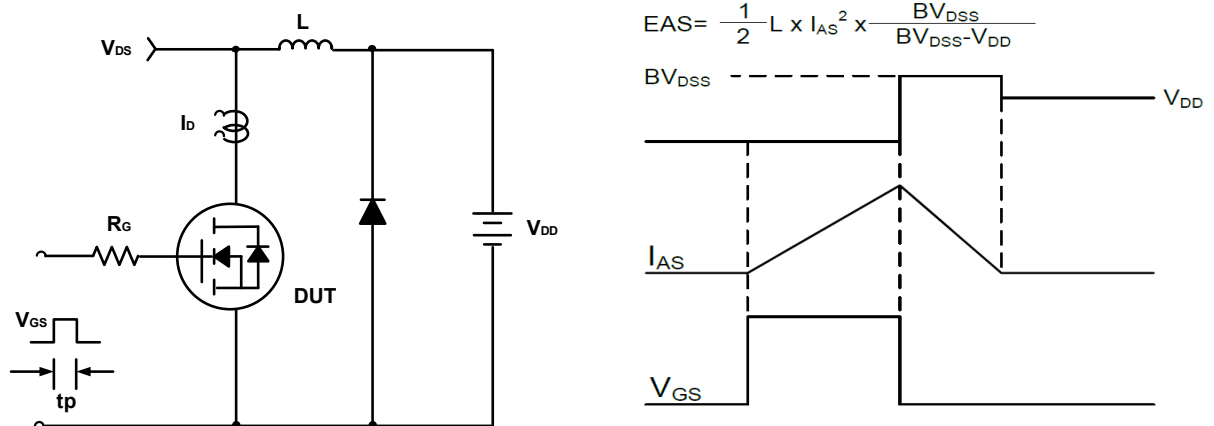
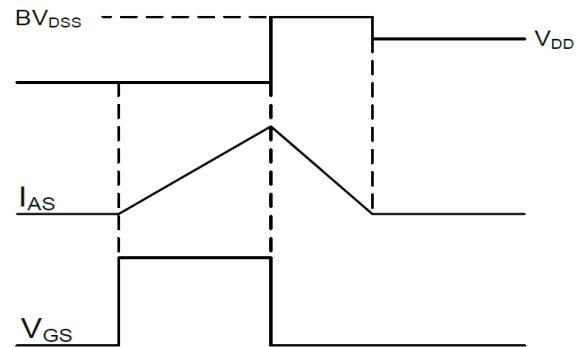


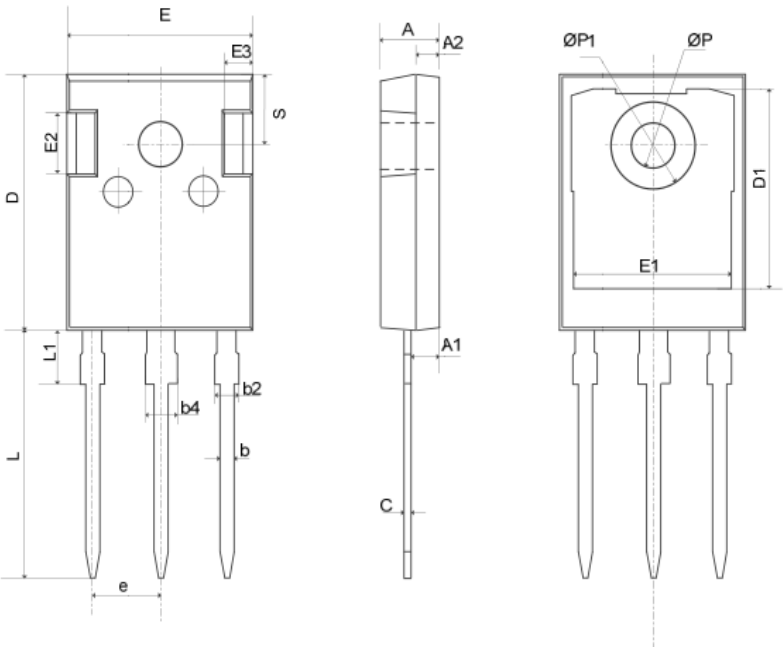
Figure B. Switching Test Circuit & Waveforms



$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$



Mechanical Dimensions for TO-247



COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	4.80	5.20
A1	2.21	2.61
A2	1.85	2.15
b	1.11	1.36
b2	1.91	2.21
b4	2.91	3.21
c	0.51	0.75
D	20.70	21.30
D1	16.25	16.85
E	15.50	16.10
E1	13.00	13.60
E2	4.80	5.20
E3	2.30	2.70
e	5.44BSC	
L	19.62	20.22
L1	—	4.30
ØP	3.40	3.80
ØP1	—	7.30
S	6.15BSC	